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MCOT128064P1V-YM	128 x	x 64 OLED Module			
Specification					
Version: 1		Date: 21/09/2017			
		Revision			
1	18/09/2017	First Issue			

Display F	Display Features			
Resolution	128 x 64			
Appearance	Yellow on Black		, HC	
Logic Voltage	3V	RoHS		
Interface	Multi	CO	ompliant	
Module Size	34.50 x 23.00 x 1.65mm			
Operating Temperature	-40°C ~ +70°C	Box Quantity	Weight / Display	
Construction	СОТ			

* - For full design functionality, please use this specification in conjunction with the MD1106G specification. (Provided Separately)

Display Accessories					
Part Number	Description	AC			

Optional Variants				
Appearance	Voltage			

General Specification

The Features is described as follow:

■ Module dimension: 34.50 × 23.00 × 1.65 mm

■ Active area: 29.42 x 14.20 mm

■ Dot Matrix: 128*64

Pixel size: 0.205 x 0.197 mm
 Pixel pitch: 0.230 x 0.222 mm
 Display Mode: Passive Matrix

■ Duty: 1/64 Duty

Display Color: Yellow

■ IC: MD1106G

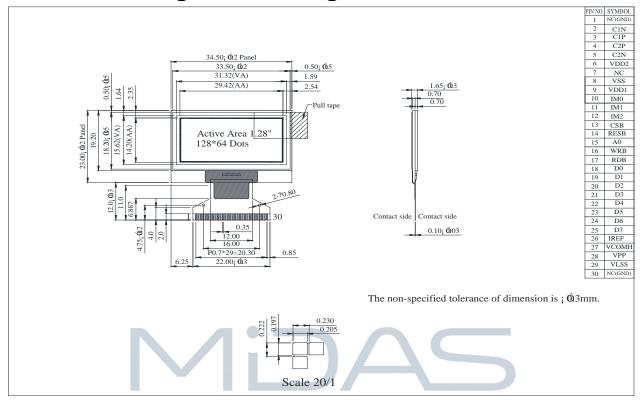


Interface Pin Function

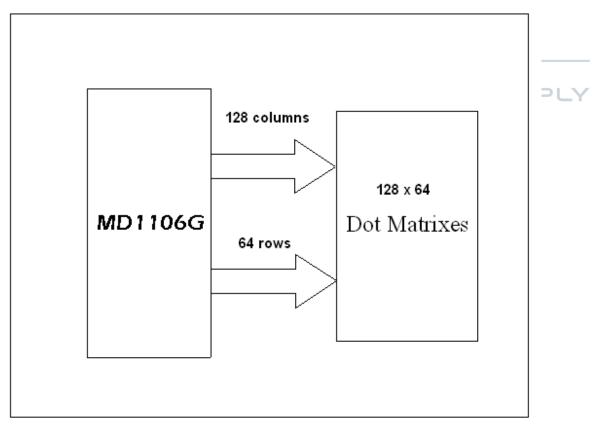
No.	Symbol	Function						
1	NC(GND)	No conne	No connection					
2	C1N		Connect to charge pump capacitor.					
3	C1P	These pinexternally		sed and shou	ıld be discon	nected when	Vpp is supp	lied
4	C2P			ımp capacito				
	CON	•		sed and shou	ıld be discon	nected when	ι Vpp is supp	lied
5	C2N	externally						
6	VDD2			ply pad for P sconnected w		• .	•	
7	NC	No conne	ection					
8	VSS	Ground.						
9	VDD1		ıpply input: 1					
10	IMO	These ar	e the MPU ir	nterface mod	e select pad	S.		
· •			8080	I ² C	6800	4-wire SPI	3-wire SPI	
11	IM1	IM0	0	0	0	0	1	
		IM1	1	1	0	0	0	
12	IM2	IM2	1	0	1	0	0	
13	CSB	active,	This pad is the chip select input. When CSB = "L", then the chip select becomes active, and data/command I/O is enabled.					
14	RESB	The rese	t	input pad. Wi			settings are	initialized.
15	DES A0	This is th data or a comman	e Data/Como	mand control	pad that de	termines whe	ether the data	a bits are
13	AU	A0 = "L": In I2C int	A0 = "H": the inputs at D0 to D7 are treated as display data. A0 = "L": the inputs at D0 to D7 are transferred to the command registers. In I2C interface, this pad serves as SA0 to distinguish the different address of OLED driver.					
16	WRB	When co 8080 MP signal. Th signal. When co terminal. When R/	nnected to a U WR ne signals or	n the data bu 6800 Series ad.	, this is activ	at the rising	pad connect edge of the rite control si	WR

$\overline{}$		
		This is a MPU interface input pad.
		When connected to an 8080 series MPU, it is active LOW. This pad is connected to the RD signal
		of the 8080 series MPU, and the data bus is in an output status when this signal is
4-7	DDD	"L".
17	RDB	When connected to a 6800 series MPU, this is active HIGH. This is used as an
		enable clock
		input of the 6800 series MPU.
		When RD = "H": Enable.
		When RD = "L": Disable.
18	D0	This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard
19	D1	MPU data bus.
20	D2	When the serial interface is selected, then D0 serves as the serial clock input pad
21	D3	(SCL) and D1
22	D4	serves as the serial data input pad (SI). At this time, D2 to D7 are set to high
23	D5	impedance.
24	D6	When the I2C interface is selected, then D0 serves as the serial clock input pad
0.5	5-7	(SCL) and D1
25	D7	serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance.
		This is a segment current reference pad. A resistor should be connected between
26	IREF	this pad and
20	IIVLI	VSS. Set the current at 18.75uA.
		This is a pad for the voltage output high level for common signals.
27	VCOMH	A capacitor should be connected between this pad and VSS.
20	\/DD	OLED panel power supply. Generated by internal charge pump.
28	VPP	Connect to capacitor. It could be supplied externally.
29	VLSS	This is a segment voltage reference pad.
29	VLOO	This pad should be connected to VSS externally.
30	NC(GND)	No connection

Contour Drawing & Block Diagram



FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Midas Displays.

Absolute Maximum Ratings

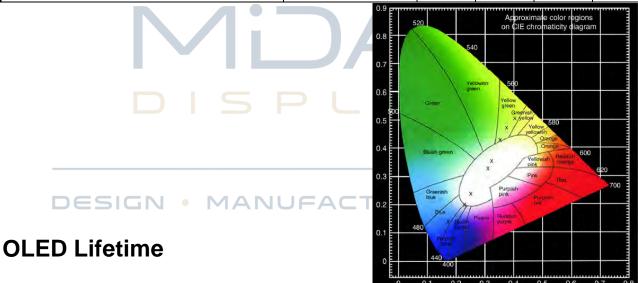
Parameter	Symbol	Min	Max	Unit
Supply Voltage for Logic	VDD1	-0.3	3.6	٧
Power supply for charge pump circuit	VDD2	-0.3	4.8	٧
Supply Voltage for Display	VPP	-0.3	14.5	٧
Operating Temperature	TOP	-40	+70	°C
Storage Temperature	TSTG	-40	+85	°C

Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD		2.8	3.0	3.3	V
Supply Voltage for Display	VCC		7	7.25	7.5	V
High Level Input	VIH	_	0.8VDD	_	VDD	V
Low Level Input	VIL	_	VSS	_	0.2VDD	V
High Level Output	VOH	_	0.8VDD	_	VDD	V
Low Level Input	NON N	FACTU	RVSS •	S	0.2VDD	V
50% Check Board operating C	urrent	VCC =7.25V	5	6	7	mA

Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160	_	_	deg
view / wigio	(Η)φ	_	160	_	_	deg
Contrast Ratio CR Dark		Dark	2000:1	_	_	_
Response Time	T rise	_	_	10	_	μs
Treeponds Time	T fall	_	_	10	_	μs
Display with 50% check	S	100	120	_	cd/m2	
CIEx(Yellow)	x,y(CIE1931)	0.45	0.47	0.49		
CIEy(Yellow)		x,y(CIE1931)	0.48	0.50	0.52	_



ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness 100cd/ m ²	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

Reliability

Content of Reliability Test

Environmenta	ıl Test			
Test Item	Content of Test	Test Condition	Applicable Standard	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs		
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 240hrs		
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs		
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs		
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	5	
Temperature Cycle Mechanical Tes	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C/80°C 30 cycles	SUPPLY	
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	_	
Others				
Static electricity test	Endurance test applying the electric stress to the terminal.	Air Discharge model ±4kv,10 times		

^{***} Supply voltage for OLED system =Operating voltage at 25 $^{\circ}\!\mathrm{C}$

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 				2.5
03	OLED black spots, white spots, contamina tion (non-display)	3.1 Round type following drawin Φ=(x+y)/2 X T		SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2	2.5
	DESI	3.2 Line type : (/	As followin	g drawing)	SUPPL	Y
		4	Length	Width	Acceptable Q TY	
		$\sim 1 \frac{w}{w}$		W≦0.02	Accept no dense	0.5
		→ L +	L≦3.0	0.02 < W ≤ 0.03	2	2.5
		20	L≦2.5	0.03 <w≦0.05< td=""><td></td><td></td></w≦0.05<>		
				0.05 < W	As round type	
04	Polarizer				,	
	bubbles	If bubbles are vi	•	Size Φ	Acceptable Q TY	
		judge using black	•	Φ≦0.20	Accept no dense	
		specifications, not easy to find, must check in		0.20<Φ≦0.50	3	2.5
		specify direction		0.50<Φ≦1.00	2	
		. ,		1.00<Φ	0	
				Total Q TY	3	

NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED bl	lack spots, white spot	s, contamination	
	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side I L: Electrode pad length:				
		6.1 General glass chi 6.1.1 Chip on panel s		ween panels:	
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	y: Chip width Not over viewing area Not exceed 1/3k	x: Chip length x≤1/8a x≤1/8a	2.5
		Olf there are 2 or mo			
			O. ACTOR		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≤1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or mo	ore chips, x is the total	l length of each chip.	

NO	Item	Criterion	AQL	
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:		
		y: Chip width x: Chip length z: Chip thickness		
		$y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$		
		6.2.2 Non-conductive portion:		
06	Glass crack	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	2.5	
		y: Chip width x: Chip length z: Chip		
		$ \begin{array}{ c c c c c c }\hline & & thickness\\ \hline y \le L & x \le 1/8a & 0 < z \le t \end{array} $		
		○If the chipped area touches the ITO terminal, over 2/3 of the ITO		
	DE	must remain and be inspected according to electrode terminal p specifications.	Y	
		⊙ If the product will be heat sealed by the customer, the alignment		
		mark not be damaged. 6.2.3 Substrate protuberance and internal crack.		
		Ÿ		
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		
		y and the second		

NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB. COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 0.65 0.65
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5 2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
12	General	12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
12	appearance	12.6 The residual rosin or tin oil of soldering (component or	2.5
		chip component) is not burned into brown or black color.	0.65
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.12.9 OLED pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	

DISPLAYS

Check Item	Classification	Criteria	
No Display	Major		
Missing Line	Major		
Pixel Short	Major		
Darker Short	Major		
Wrong Display	• MANUEA Major	AC PROPERTY OF	PL
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major		
		A Normal B Dark Pixel C Light Pixel	

Precautions in use of OLED Modules

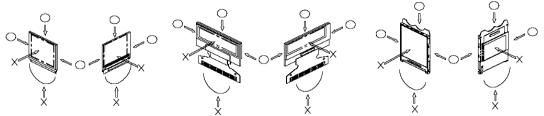
- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Midas has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

2. Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Midas Displays. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.